



Minutes of S-1 Steering Committee/ General Session

Tuesday, 17 May, 2005

Chateau Sonesta Hotel

New Orleans, LA

SCOPE

S-1 Passive Component Steering Committee's scope: To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers.

An attendance sheet was circulated. The attendance was as follows:.

Attendees:

NAME	COMPANY
Frank B. Hayward	American Technical Ceramics
Chris Reynolds	AVX
Dan Giblin	Cooper Bussmann
Laird Macomber	Cornell Dubilier
Ed Mikoski	EIA/ECA
Jay Gatmaitan	ENDEVCO
Phil Diglio	EPCOS Inc
Mike Lauri	IBM
Mark Strandquest	IHS
Jason Young	KEMET
Lucy Lee	KEMET Electronics
Michael Griffith	KOA
Stephen Olster	Mini-Systems Inc.
Karun Malhotra	Murata Electronics
Terry Don Charles	Panasonic
Len Metzger	Panasonic
Carl Lindquist	San-O-Industrial Corp
Bill Gisseler	TDK
Michael Cannon	TDK Corp.
Ted Coler	Vishay
David Richardson	Vishay
Dave Toomey	Vishay
Dave Ritchey	Yageo

A quorum was present.

<u>Member Organizations Present</u>	<u>Present at this meeting</u>	<u>Present at Spring2005 Summit</u>	<u>Present at Fall2004 Summit</u>
American Technical Ceramics.	Y	Y	Y
AVX	Y	Y	Y
Cooper Bussmann	Y	Y	Y
Cornell Dubilier	Y	Y	Y
Epcos	Y	Y	N
IBM	Y	Y	N
Kemet	Y	Y	Y
KOA Speer Electronics	Y	Y	Y
Mini-Systems Inc.	Y	Y	Y
Murata Electronics	Y	Y	Y
Panasonic	Y	Y	Y
San-O-Industrial Corp	Y	Y	Y
TDK	Y	Y	Y
Vishay	Y	Y	Y
Yageo	Y	Y	Y

^Indicates activated as member of committee

<u>Member Organizations Absent</u>	<u>Present at This Meeting?</u>	<u>Present at Spring2005 Summit</u>	<u>Present at Fall2004 Summit</u>
AEM, Inc.	N	Y	Y
Intel Corporation	N	Y	Y^
SEI Electronics, Inc.	N	N	Y

* Indicates not used in determination of quorum due to record of non-attendance

<u>Other Organizations Present</u>
EIA/ECA
Endevco
IHS

1.0 Meeting called to order at 8:05am

2.1 Membership Intro were conducted and roster circulated.

2.2 Approval of Agenda and previous minutes – Approved

Note: previous minutes had 2 errors which need fixing.

Sub-committee reports in section 3 for P10 and P2.1 need revision.

For P10 PN4946 needs to change to PN4996

For P2.1 EIA 591 needs to change to EIA521

2.3 Correspondance – none received

2.4 Review of Committee Scope - the old scope was put up and reviewed. It was voted on and accepted as previously written as follows:

3.0 Sub-Committee and Working Group

CE2.0/3.0 – Ed gave brief update on connectors and sockets, new chairman is now Frank Refino of Molex. Group is working on test procedures and revising EIA364.

P-14 Fuses – PN5072 was balloted and approved. PN 5073 was balloted and had 1 negative comment which is being addressed, PN5074 Applications Guide is being revised.

P-2.2 and P2.4 Aluminum, Film, and Mica Capacitors – PN-4283 (EIA-797), Aluminum Electrolytic Capacitor Application Guideline. Is currently out for ballot now with comments due 6/27/05
PN 4985, Aluminum Electrolytic Chip Capacitor with Polymer Cathode currently out for ballot with comments due 7/05/05
PN 4984 Aluminum Electrolytic Capacitor Qualification Specification currently out for ballot with comments due 7/05/05
Revising RS376 into electronic form which will then be used to generate a SMT version.

P-10 IPD – PN4944 RC Test Performance Specification was balloted.
PN 4996 IPD Chip Scale Package Test is in revision.

P-1 Resistors – Working to finalize EIA 575 and 576 Thick and Thin Film Resistor Specs
Revising EIA 886 (PN5090) Thick Film Arrays and EIA 887(PN5091) Thin Film Arrays
CB19 being reviewed to include resistor products.
Revising EIA703 for the acceptance criteria for ESD testing.

P-3 Inductors – Revising EIA 944 and EIA 945
Also trying to get test specification information on beads from all manufactures.

P4 Mechanical Outlines – Many different types of outlines being submitted (resistors, capacitors, inductors etc) Any device with more than 2 pins today is a problem, but database will need to change to accommodate arrays, IPD's etc...
Ed Mokoski took us through the ECA website for mechanical outlines.

P-2.1 Ceramic Working Group – Revision of 469-D currently out for ballot. Due 6/27/05.
Revision to EIA 595(PN5094) and EIA 521(PN=??) in subcommittee. Revision to EIA 481 needed in ACH committee. The low ESL test spec being revised.

P-2.5 Tantalum Working Group – PN4904 Polymer Specification was balloted and closed 5/5/05. To be issued soon by ECA.
Combining EIA 535BAAC with 535BAAE Standard and low ESR tantalums since they are similar.
EIA 809 being revised, EIA 717 being revised. Also a niobium oxide spec (PN5075) is being generated.

Automated Component Handling – not present but this committee is working on matrix tray specs, and also pin 1 indicators on >12mm size devices in trays.

G-11 – Component Parts Committee – no report was given, next meeting is next week.

Soldering Technology – no formal report but Ed Mikoski stated that its very important to participate due to its importance for JEDEC and to hear our passives voice in these committees.
Revising IPC/EIA-J-STD-002C to add lead free solderability parameters.

Engineering Dept Executive Committee – meeting will be held tomorrow to discuss changes and cross committee inputs.

4.0 Environmental Update – ECA Ed Mikoski will give the update at ECA dinner, the materials declaration guide was published and will be shared at this meeting.

5.0 New Business

S1 Committee should send a letter of thanks to Keith Siemens of Visteon for his outstanding contributions to ECA and this particular committee over the years. Dave Richardson to draft a letter to send by next meeting.

It was brought to the attention of this committee that EIA 481 tape and reel spec is incorrect and Quickly needs to be fixed. The reverse polarity for tantalums in the tape needs revising, along with the large size ceramics being rotated in the tape. It was noted that the ceramic and tantalum committees will formulate a response to be taken to ACH committee meeting on Thursday 5/19/05.

It was brought up that a Component Bulletin should be written on counterfeit components in the industry. A sub-committee was formed and AVX Chris Reynolds will lead this task group, other Participants will include Kemet, KOA, Vishay, AVX, and IBM. A PN number will be taken out to start this activity.

CB19 also needs to be revised to include other component types like tantalums, inductors, resistors etc....A sub-committee was formed and IBM Mike Lauri will lead this task group to Get this bulletin revised. A new PN will be taken out for this revision.

A recommendation was made to also make a component bulletin on whisker length recommendations to iNEMI and other organizations. A sub-committee was formed lead by Karun Malhotra of Murata and to include AVX, Kemet, Vishay, TDK, Murata and KOA.

6.0 Future Meetings

- Fall 2005 – Memphis, Tn at the Radison Hotel
- Spring 2006 – Fort Lauderdale, FL(primary), Orlando (secondary)

7.0 Meeting Adjourned

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

Mike Lauri
Chairman

Dave Richardson
Co-Chairman/Secretary